

MA4ZD14

Silicon epitaxial planar type

For high speed switching

■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Low forward voltage: $V_F < 0.40$ V

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse-voltage	V_{RRM}	20	V
Forward current	Single	100	mA
	Double *1		
Peak forward current	Single	300	mA
	Double *1		
Non-repetitive peak forward surge current *2	Single	1	A
	Double *1		
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Value of each diode in double diodes used.

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

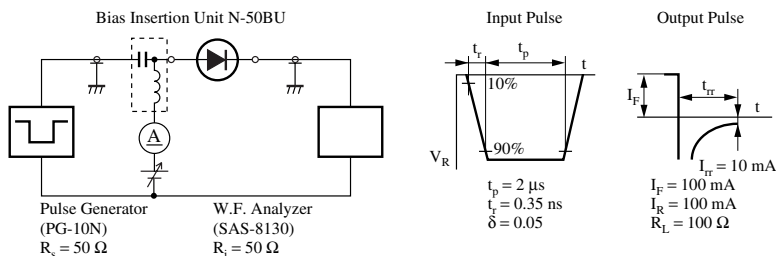
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_R	$V_R = 10$ V			20	μA
Forward voltage	V_{F1}	$I_F = 5$ mA			0.27	V
	V_{F2}	$I_F = 100$ mA			0.40	
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		25		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100$ Ω		3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz.

4.*: t_{rr} measurement circuit

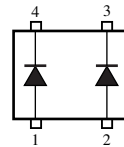


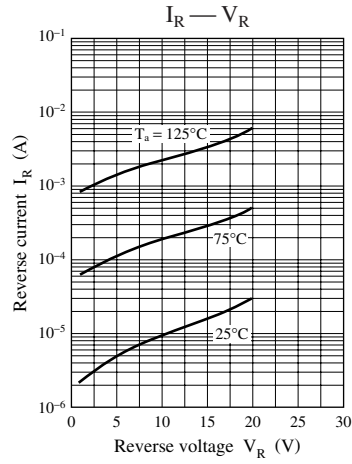
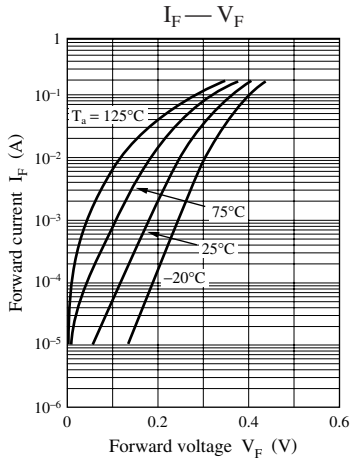
■ Package

- Code
SMini4-F1
- Pin Name
1: Anode 1 3: Cathode 2
2: Anode 2 4: Cathode 1

■ Marking Symbol: M5D

■ Internal Connection





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